ABSTRACT

The present invention provides a circuit board including a plurality of pads for mounting a semiconductor device with bumps and a plurality of wires drawn from the respective pads, a mounting structure for the semiconductor device with bumps, and an electro-optic device and an electronic device. The circuit board has a region where the pitch in the longitudinal direction and the lateral direction of the plurality of pads are different from each other and the wires are preferentially drawn from a wider pitch side of the longitudinal direction or the lateral directions of the pads.